

HV SKAI 2

Three-phase IGBT inverter

SKAI 45 A2 GD12-WDI

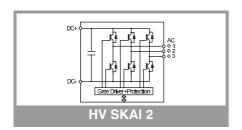
Features

- · Optimized for HEV and EV
- · High power density
- High overload capability
- Compact integration in IP67 enclosure:
 V, I, T sensors
 Gate driver with protection features
 Active DC-link discharge unit
 EMI filters
 Liquid cooling
 DC-link capacitor
 Suitable environmental conditions
 in accordance to ISO
 16750-(B,F)-N-K-D-Z-IP(6K7;6K9K)

Typical Applications*

- · Commercial application vehicle
- Hybrid vehicle
- Battery driven vehicles (not suitable for mains applications)

No. 14282032



Characteristics						
Symbol	Conditions		min.	typ.	max.	Unit
Electrical Data						•
V _{isol}	DC, t = 1 s, (routine test acc. EN 50178)			3000		٧
	DC, t = 1 min, (type test, acc. ISO 6469-3)			4000		V
V _{CC}	DC supply voltage			750	800	V
I _{nom}	rms @ nominal conditions: $dV/dt = 10I/min, 50\%$ Glykol/50% H_20 , $f_{sw} = 6kHz$, $V_{CC} = 750V$, $V_{out} = 350V$ rms, $f_{out} = 50Hz$, $cos(phi) = 0.85$, $T_{coolant} = 60$ °C, $T_{air} = 65$ °C			300		А
f _{sw}	Switching frequence	у	1		12	kHz
C _{DC}	DC-link capacitanc	е	0.9		1.25	mF
C _y	EMI capacitor; DC	to enclosure		0.66		μF
R _F	DC+ to enclosure,	DC- to enclosure		6		MΩ
R _{BL}	DC+ to DC-			0.33		MΩ
Mechanic	al Data					
Weight				13.9		kg
Height				109		mm
Width				244		mm
Length				475		mm
Mt	AC / DC terminals (•	13	14	15	Nm
M _c	Cover of terminal box (M5x16 flat-head-screw)		3.5	4	4.5	Nm
M _{cg}	AC / DC cable gland thread engagemen	ds (at 7mm length of t)			20	Nm
Me	Assembly of	M8 screw			20	Nm
	enclosure; thread (I): > 15mm	M6 screw	- 10		14	Nm
M _{gnd}	Ground connection		13	14	15	Nm
Hydraulic		/ : 1				1
dp	Pressure drop@ 10l T _{coolant} = 25°C			100		mbar
р	Operating pressure				2	bar
V _{Coolant}	Coolant quantity of integrated cooling circuit			300		cm ³
Р	Power dissipation t conditions	o coolant; nominal		3.5		kW
Environm	Environmental Data					
T _{stg}	Storage temperatur	re	-40		85	°C
T _{no}	Non operating temperature range		-40		105	°C
T _{air}	Operating range, derating for T _{air} > 65°C with -3A / °C		-40		105	°C
T _{coolant}	Operating range, derating for T _{coolant} > 60°C		-40		75	°C
IP	Enclosure protection level			IP67		
	With external connector protection			IP6K9K		
Altitude	V _{CC} = 800V 4000			m		
Active Dis	charge Unit					1
t _d	Discharge time to V _{CC} < 60V				5	S
R _{dis}	PTC discharge resi	stor (at 25°C)	245	350	455	Ω



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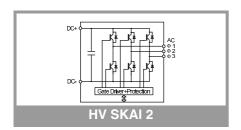
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Characte	ristics					
Symbol	Conditions		min.	typ.	max.	Unit
Interface I	Parameters					ı
V _s	Auxiliary supply vol	tage primary side	8		32	V
I _{S0}	Auxiliary supply current primary	Supply current @ Vs = 12V			900	mA
	side without driving the IGBT gates	Supply current @ Vs = 24V			450	mA
Is	Auxiliary supply current primary side with IGBT	Supply current @ Vs = 12V			2100	mA
	gate driving	Supply current @ Vs = 24V			1050	mA
V_{iH}	Input signal voltage	(HIGH)	0.7 * Vs		Vs + 0.3	V
V_{iL}	Input signal voltage	(LOW)	GND - 0.3		0.3 * Vs	V
t _{POR}	Power-on reset cor	npleted			5	S
t _{pRESET}	Error reset time				5000	ms
Controller	Switching Parame	eters				
t _{d(on)IO}	Input-output turn-or	n propagation time		0.5	8.0	μs
t _{d(off)IO}	Input-output turn-of	f propagation time		0.5	8.0	μs
t _{jitter}	Signal transfer prim	n - sec (total jitter)			50	ns
t _{SIS}	Short pulse suppre	ssion time	0.2	0.25	0.45	μs
t _{et}	Input impulse extension time		0.9	1	1.1	μs
$t_{d(err)DSCP}$	Error input-output propagation time for DSCP error		0.2		6	μs
t _{d(err)OCP}	Error input-output propagation time for OCP error			4	20	μs
t _{d(err)} TMP	Error input-output propagation time for temperature error				50	ms
t _{TD}	Top-Bot interlock d	ead time		2.5	2.6	μs
t_{bl}	V _{CE} monitoring blan	iking time		5	5.1	μs
Protection	n Functions					
T _{DCBtrip}	Over temperature pon DCB	protection trip level	120			°C
T _{RelDCBtrip}	Release temperatu overtemperature tri		85			°C
V_{DCtrip}	DC-Link voltage trip	olevel	800			V
V _{VStrip}	Under voltage prote board primary side	ection trip level of			8	V
V _{VSrst}	Threshold voltage I after failure event	evel for driver reset	8			V
I _{TRIPSC}	Overcurrent trip lev	el	567			A _{PEAK}
l _{outsens}	AC sensing range		-616		616	Α
m _{loutsens}	Gradient of output current sensing		16.20	16.70	17.21	mV/A
BW _{loutsens}	Bandwidth (-3dB) of I _{AC} sensing			17		kHz
V _{DCsens}	Measurable DC-link voltage		0		1000	V
m _{VDCsens}	Gradient of DC-link voltage sensing		9.80	10.00	10.20	mV/V
BW _{VDCsens}		cc voltage sensing		98		kHz
T _{DCBsens}	Temperature sensi		30		150	°C
m _{TDCBsens}	Gradient of temperature sensing on DCB			83.3		mV/°C
BW _{TDCBsen}	Bandwidth (-3dB) of temperature sensing on DCB			1		Hz

Signal Connector

PIN	Signal	Function	Specifications	
X1:01	PWR_VP	INPUT Auxiliary power supply / battery "+"	Supply voltage V _s	
X1:02	PWR_GND	Auxiliary power supply ground	Ground of auxiliary power supply	
X1:03	DC_LINK_DISCHAR GE	INPUT	HIGH, NOT CONNECTED (n.c.) or module not supplied with Auxiliary power = DC Link discharge active	
			LOW = DC Link discharge disabled	
			(internal pull-up resistor, external pull-up resistor required as well)	
X1:04	CMN_HALT	INPUT/OUTPUT	All connected units have to change the signal mode to "dominant" if following happens:	
			The unit is not ready to operate	
			Error happened	
			All connected units must be able to process (read) the signal. In case of recognised dominant signal, following steps need to be performed:	
			The unit must be switched to a defined safe operation mode	
			The unit must interrupt the main process unitl a recessive signal has been recognised	
			LOW (dominant) = not ready to operate	
			HIGH (recessive) = ready to operate	
X1:05	CMN_TEMP_GND	Ground for temperature sensor signal CMN_TEMP	Internally connected to PWR_GND	
X1:06	HB1_TOP	INPUT Switching PWM signal [push/pull]	Digital PWR_VP logic	
			LOW = IGBT off	
			HIGH = IGBT on	
X1:07	HB1_BOT	INPUT	Digital PWR_VP logic	
		Switching PWM signal [push/pull]	LOW = IGBT off	
			HIGH = IGBT on	
X1:08	HB2_TOP	INPUT Switching PWM signal [push/pull]	Digital PWR_VP logic	
			LOW = IGBT off	
			HIGH = IGBT on	
X1:09	HB2_BOT	INPUT	Digital PWR_VP logic	
		Switching PWM signal [push/pull]	LOW = IGBT off	
			HIGH = IGBT on	
X1:10	HB3_TOP	INPUT Switching PWM signal [push/pull]	Digital PWR_VP logic	
			LOW = IGBT off	
			HIGH = IGBT on	
X1:11	HB3_BOT	INPUT Switching PWM signal [push/pull]	Digital PWR_VP logic	
			LOW = IGBT off	
			HIGH = IGBT on	
X1:12	Reserved			

PIN	Signal	Function	Specifications
X1:13	PWR_VP	INPUT Auxiliary power supply / battery "+"	Supply voltage V _s
X1:14	PWR_GND	Auxiliary power supply ground	Ground of auxiliary power supply
X1:15	CMN_GND	Ground for CMN_HALT and DC_LINK_DISCHARGE	Internally connected to PWR_GND
X1:16	CMN_TEMP	OUTPUT Temperature sensor signal CMN_TEMP	This pin is used to transmit the temperature sensor analog signal. Max. output current: 4mA. Nominal voltage range: 010V;
X1:17	Reserved		
X1:18	HB1_GND	Ground for HB1_TOP, HB1_BOT	Internally connected to PWR_GND
X1:19	Reserved		
X1:20	HB2_GND	Ground for HB2_TOP, HB2_BOT	Internally connected to PWR_GND
X1:21	Reserved		
X1:22	HB3_GND	Ground for HB3_TOP, HB3_BOT	Internally connected to PWR_GND
X1:23	Reserved		
X1:24	PWR_VP	INPUT Auxiliary power supply / battery "+"	Supply voltage V _s
X1:25	PWR_GND	Auxiliary power supply ground	Ground of auxiliary power supply
X1:26	Reserved		
X1:27	CMN_DCL	OUTPUT DC-Link voltage signal [analog]	This pin is used to transmit the DC-Link voltage level.
			Max. output current: 4mA
			Nominal voltage range: 0+10V
			Bandwidth (-3dB) for load resistance of $2k\Omega$:
			see datasheet value BW _{VDCsens} .
X1:28	CMN_DCL_GND	Ground for DC-Link voltage signal CMN_DCL	Internally connected to PWR_GND
X1:29	HB1_I	OUTPUT Current sensor out for HB1 [analog]	Max. output current: 4mA
			Nominal voltage range: -10 +10V
			Bandwidth (-3dB): 17kHz at load resistance of $2k\Omega$;
			(18kHz at load resistance of 10kΩ);
X1:30	HB1_I_GND	Ground for HB1_I	Internally connected to PWR_GND
X1:31	HB2_I	OUTPUT Current sensor out for HB2 [analog]	Max. output current: 4mA
			Nominal voltage range: -10 +10V
			Bandwidth (-3dB): 17kHz at load resistance of $2k\Omega$;
			(18kHz at load resistance of 10kΩ);
X1:32	HB2_I_GND	Ground for HB2_I	Internally connected to PWR_GND
X1:33	HB3_I	OUTPUT	Max. output current: 4mA
		Current sensor out for HB3	Nominal voltage range: -10 +10V
		[analog]	Bandwidth (-3dB): 17kHz at load resistance of $2k\Omega$;
			(18kHz at load resistance of 10kΩ);
X1:34	HB3_I_GND	Ground for HB3_I	Internally connected to PWR_GND
X1:35	Reserved		

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Power Connectors

Terminal	Function	cable harness Ø Cu/mm ²	V rated terminal	I rated terminal
DC +	HVDC Bus "+"	@ 50	900V DC	300A rms
DC -	HVDC Bus "-"	@ 50	900V DC	300A rms
L1	Phase L1	@ 50	900V DC	300A rms
L2	Phase L2	@ 50	900V DC	300A rms
L3	Phase L3	@ 50	900V DC	300A rms

Coolant Fittings

Terminal	Function
IN	Coolant Inlet
OUT	Coolant Outlet

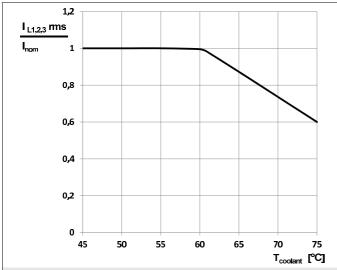


Fig. 1: Normalized output current vs. coolant temperature (temperature at coolant inlet "IN")

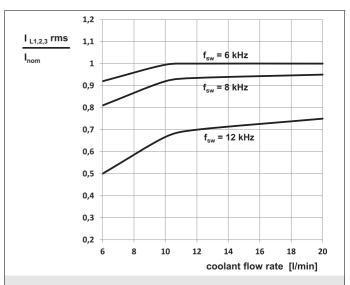


Fig. 2: Normalized output current vs. coolant flow

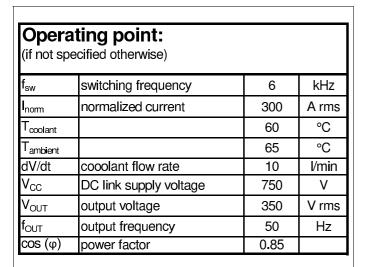


Fig. 3: Legend

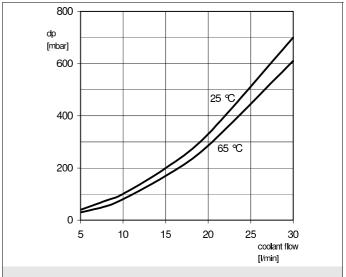


Fig. 4: Pressure drop characteristic

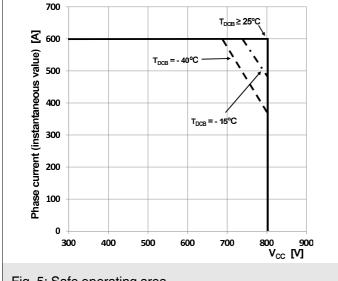


Fig. 5: Safe operating area

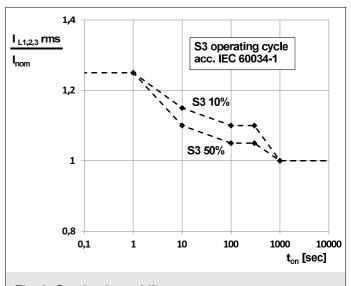


Fig. 6: Overload capability

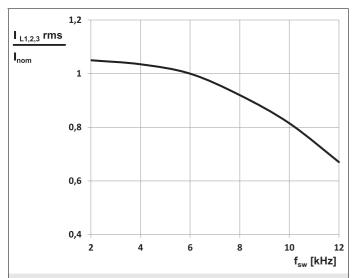


Fig. 7: Normalized output current vs. switching frequency f_{sw}

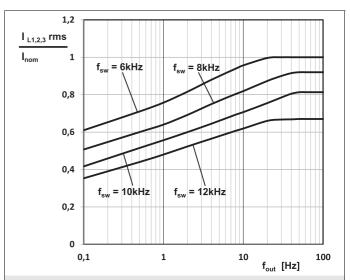
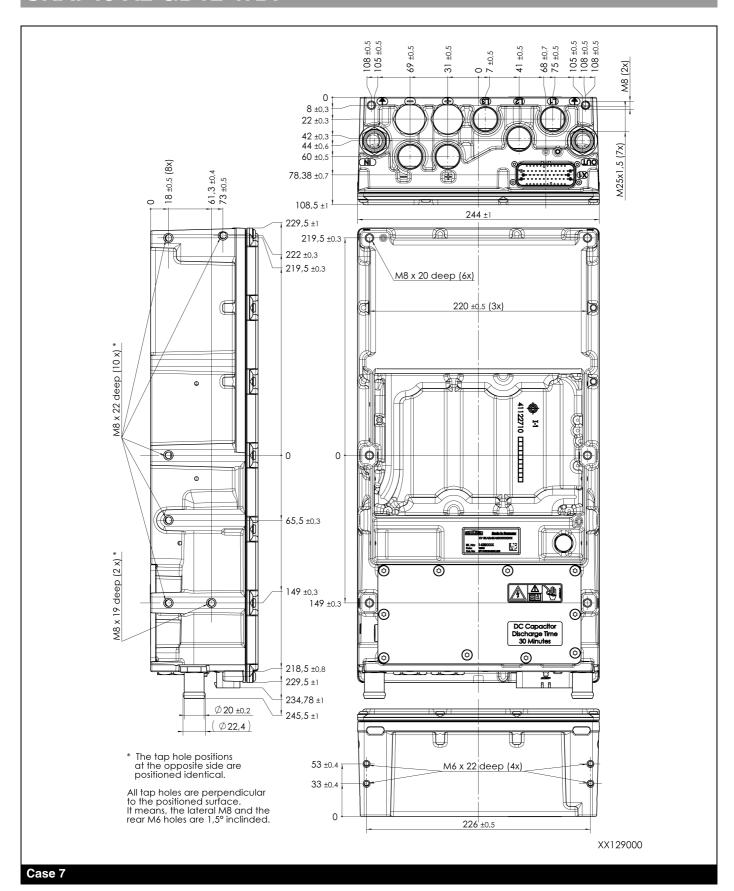
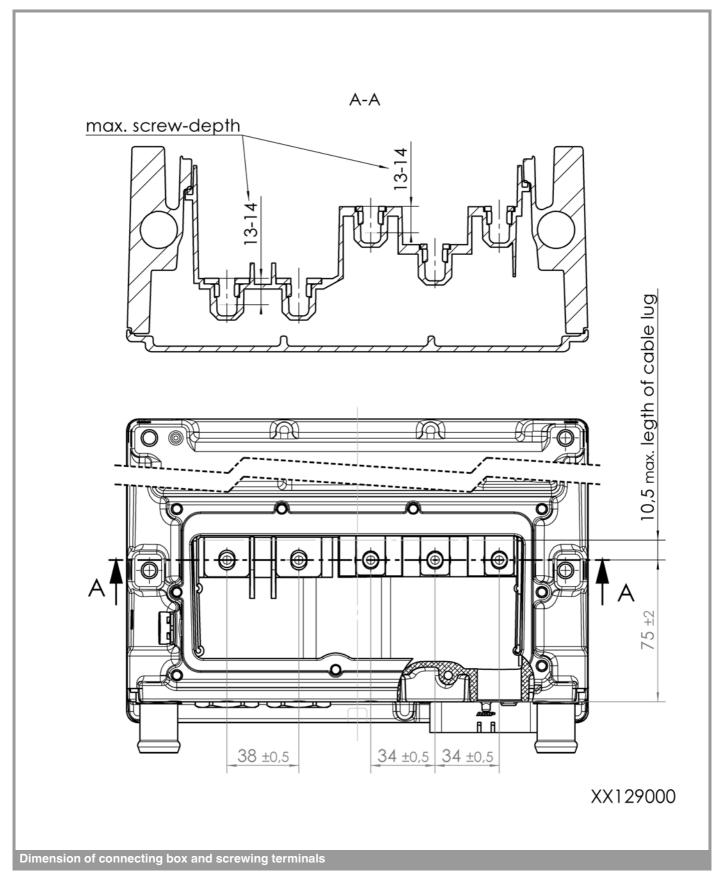


Fig. 8: Normalized output current vs. inverter output frequency



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This is an electrostatic discharge sensitive device (ESDS), international standard IEC 60747-1, Chapter IX

^{*} The specifications of our components may not be considered as an assurance of component characteristics. Components have to be tested for the respective application. Adjustments may be necessary. The use of SEMIKRON products in life support appliances and systems is subject to prior specification and written approval by SEMIKRON. We therefore strongly recommend prior consultation of our staff.